

In the Claims:

Please amend the claims as follows:

1-12 (Canceled)

13. (New) A packaged semiconductor component comprising:

a substrate; and

a chip mounted on the substrate, wherein at least a rear side and side edges of the chip are enclosed by a molding covering, molding material used for the molding covering being connected to the substrate in a manner forming a compact unit;

wherein the substrate includes a sponge-like structure that is provided with porous openings that extend from a surface to a depth, such that the molding material penetrates into the substrate.

14. (New) The packaged semiconductor component as claimed in claim 13 wherein the molding material penetrates into the substrate through capillary action.

15. (New) The packaged semiconductor component as claimed in claim 13, wherein the chip is mounted on an upper surface of the substrate and wherein the entire upper surface of the substrate includes the sponge-like structure.

16. (New) The packaged semiconductor component as claimed in claim 15, wherein all surfaces of the substrate include the sponge-like structure.

17. (New) The packaged semiconductor component as claimed in claim 13, wherein the sponge-like structure has been produced by partial removal of an epoxy resin portion in the substrate.

18. (New) The packaged semiconductor component as claimed in claim 17, wherein the sponge-like structure has been produced by wet or dry etching.

19. (New) The packaged semiconductor component as claimed in claim 17, wherein the substrate is partially covered with a soldering resist mask.

20. (New) The packaged semiconductor component as claimed in claim 13, wherein the sponge-like structure has been produced by mechanical surface processing of the substrate.

21. (New) A method for producing a packaged electronic component, the method comprising:

providing a package substrate;

modifying the package substrate to create a sponge-like structure over at least a portion of an upper surface of the package substrate;

mounting an electronic component on the upper surface of the package substrate; and

applying a molding material to enclose at least side edges of the chip such that portions of the molding material penetrate into the sponge-like structure of the package substrate.

22. (New) The method as claimed in claim 21 wherein the molding material penetrates into the sponge-like structure of the package substrate through capillary action.
23. (New) The method as claimed in claim 21, wherein the entire upper surface of the package substrate is modified to include the sponge-like structure.
24. (New) The method as claimed in claim 23, wherein all surfaces of the package substrate are modified to include the sponge-like structure.
25. (New) The method as claimed in claim 21, wherein modifying the package substrate comprises producing the sponge-like structure by partial removal of an epoxy resin portion in the substrate.
26. (New) The method as claimed in claim 21, wherein modifying the package substrate comprises performing a wet or dry etch.
27. (New) The method as claimed in claim 21, wherein modifying the package substrate comprises performing a mechanical surface processing of the substrate.
28. (New) The method as claimed in claim 21, wherein, after mounting the electronic component, the package substrate and the electronic component are preheated at least to the melting point of the molding compound before the application of the molding material.

29. (New) The method as claimed in claim 21, wherein the electronic component, the package substrate and the molding material are subjected to heat treatment after the application of the molding material.

30. (New) The method as claimed in claim 29, wherein the heat treatment is effected at a temperature around the melting point of the molding material.

31. (New) The method as claimed in claim 21, wherein, before the mounting the electronic component, the package substrate is partially coated with a thin layer of molding compound and subjected to heat treatment at a temperature around or above the melting point of the molding material.

32. (New) The method as claimed in claim 31, wherein the molding material is printed or dispensed onto the substrate.